

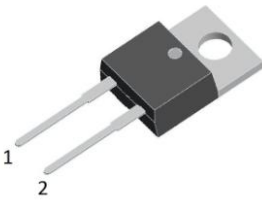
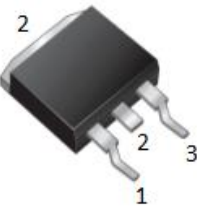

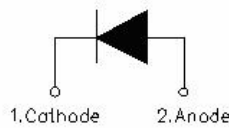
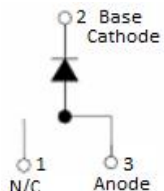
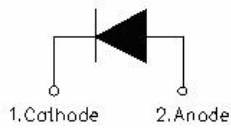
ST30100/STB30100/STF30100 SCHOTTKY RECTIFIER

Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features

- 150 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

ST30100	STB30100	STF30100
		
		
TO-220AC	D ² PAK	ITO-220AC

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V _{RRM}	-	100	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _R			
Average Rectified Forward Current	I _{F(AV)}	50% duty cycle @T _c =100°C, rectangular wave form	30	A
Peak One Cycle Non-Repetitive Surge Current	I _{FSM}	8.3ms, Half Sine pulse, T _C = 25 °C	300	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop*	V _{F1}	@ 5A, Pulse, T _J = 25 °C	0.47	-	V
		@ 10A, Pulse, T _J = 25 °C	0.54	-	
@ 15A, Pulse, T _J = 25 °C		0.61	0.68		
@ 20A, Pulse, T _J = 25 °C		0.68	-		
@ 30A, Pulse, T _J = 25 °C		0.82	0.90		
	V _{F2}	@ 5A, Pulse, T _J = 125 °C	0.38	-	V
		@ 10A, Pulse, T _J = 125 °C	0.51	-	
		@ 15A, Pulse, T _J = 125 °C	0.58	0.65	
		@ 20A, Pulse, T _J = 125 °C	0.64	-	
		@ 30A, Pulse, T _J = 125 °C	0.74	0.80	
Reverse Current*	I _{R1}	@V _R = 70V, T _J = 25 °C	0.012	-	mA
		@V _R = 100V, T _J = 25 °C	0.030	1	
	I _{R2}	@V _R = 70V, T _J = 125 °C	10	-	mA
		@V _R = 100V, T _J = 125 °C	15	75	
Junction Capacitance	C _T	@V _R = 5V, T _C = 25 °C f _{SIG} = 1MHz	845	-	pF

* Pulse width < 300 μs, duty cycle < 2%

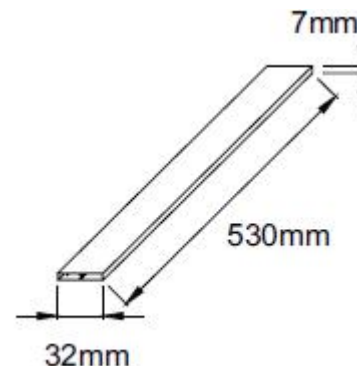
Thermal-Mechanical Specifications:

Characteristics	Symbol	ST30100	STB30100	STF30100	Units
Junction Temperature	T _J	-55 to +150			°C
Storage Temperature	T _{stg}	-55 to +150			°C
Typical Thermal Resistance Junction to Case	R _{θJC}	2.0	2.0	5.0	°C/W

Tube Specification

Device	Package	Weight	Shipping
ST30100	TO-220AC	1.6g	50pcs / tube
STB30100	D ² PAK	1.85g	800pcs / reel
STF30100	ITO-220AC	1.6g	50pcs / tube

Tube Specification(TO-220AC/ITO-220AC)



For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Ratings and Characteristics Curves

Figure 1
Typical Forward Characteristics

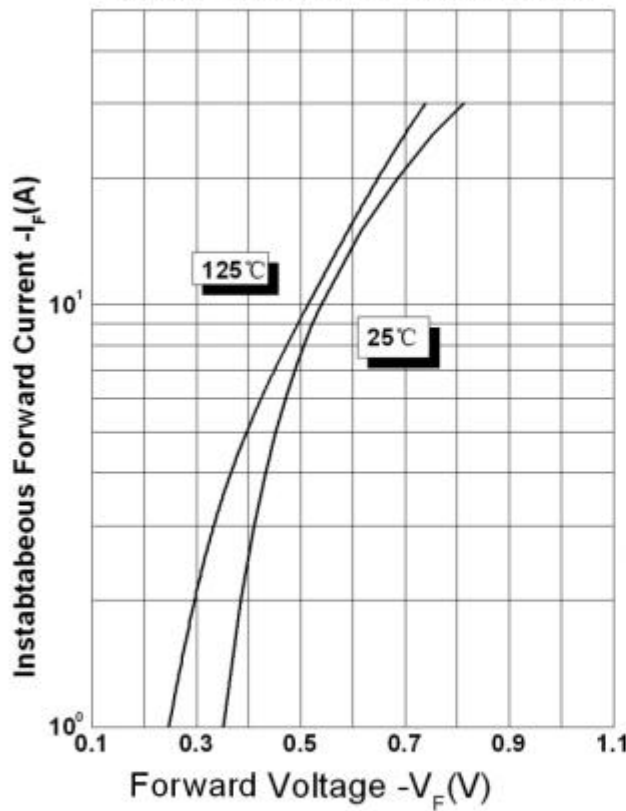


Figure 2
Typical Reverse Characteristics

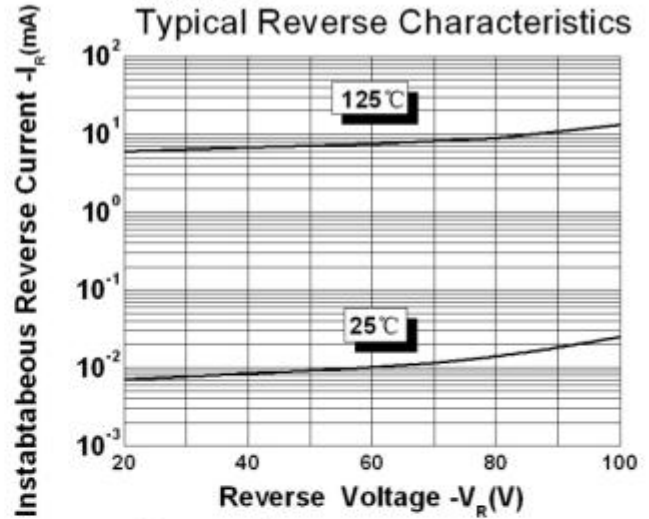
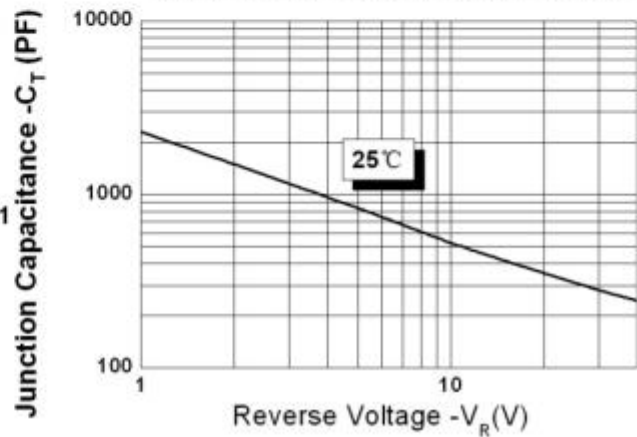
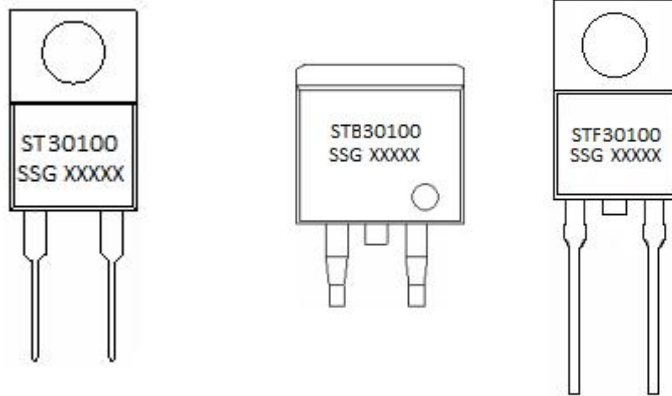


Figure 3
Typical Junction Capacitance



Marking Diagram

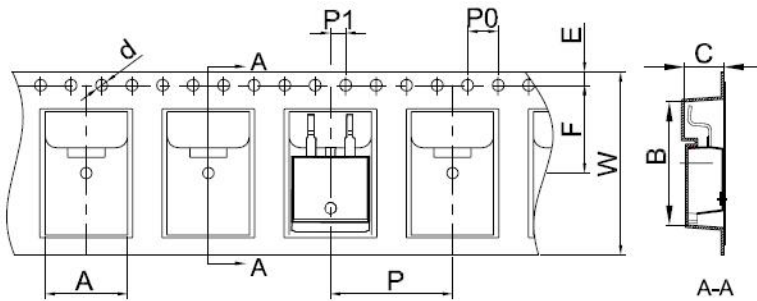


Where XXXXX is YYWWL

ST = Device Type
B/F = Package type
30 = Forward Current (30A)
100 = Reverse Voltage (100V)
SSG = SSG
YY = Year
WW = Week
L = Lot Number

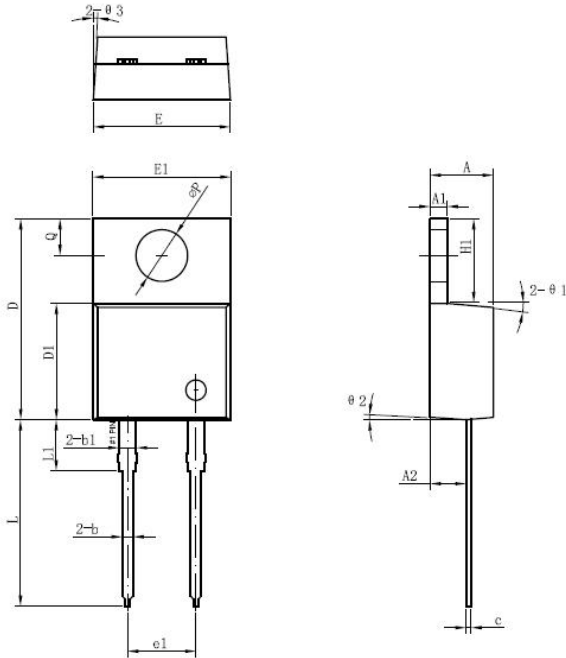
Cautions: Molding resin
Epoxy resin UL:94V-0

Carrier Tape Specification D²PAK



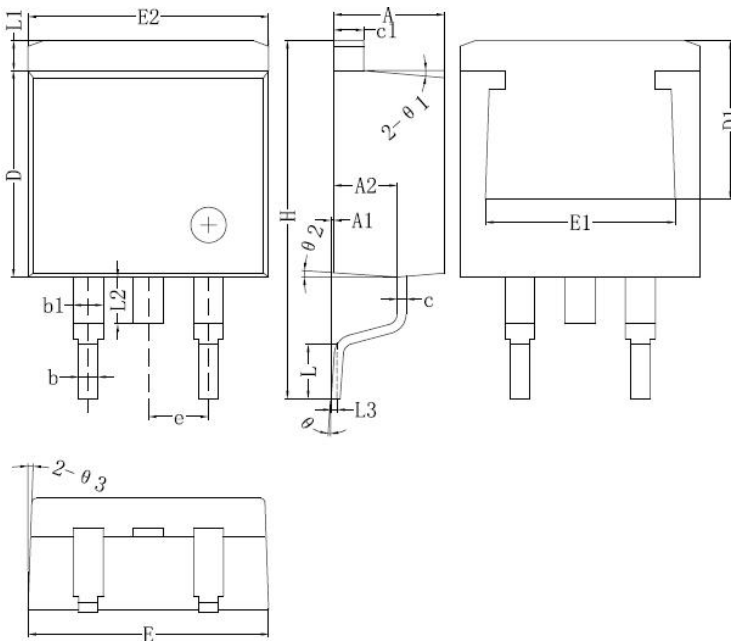
SYMBOL	Millimeters	
	Min.	Max.
A	10.70	10.90
B	16.03	16.23
C	5.11	5.31
d	1.45	1.65
E	1.65	1.85
F	11.40	11.60
P0	3.90	4.10
P	15.90	16.10
P1	1.90	2.10
W	23.90	24.30

Mechanical Dimensions TO-220AC



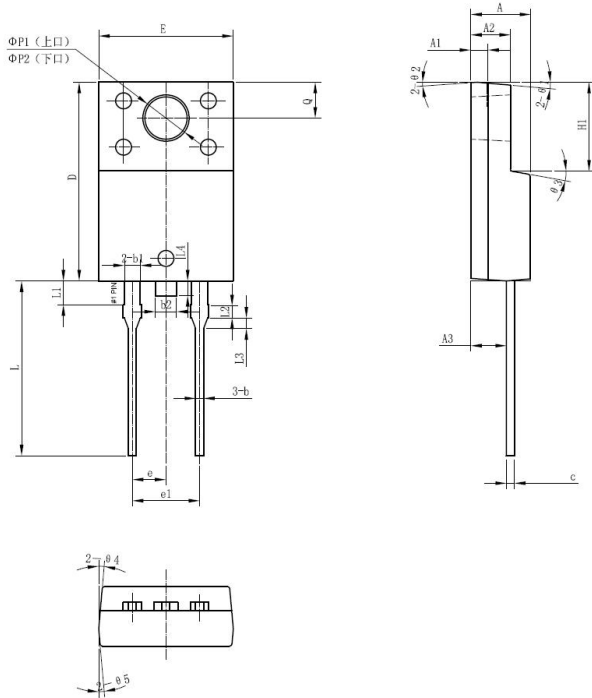
Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.47	4.70	4.85
A1	1.17	1.27	1.37
A2	2.52	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
D	14.64	14.94	15.24
D1	8.50	8.07	8.90
E	10.01	10.16	10.31
E1	9.98	10.18	10.38
e1	4.98	5.08	5.18
H1	6.04	6.24	6.44
L	13.00	13.86	14.08
L1	3.56	3.80	3.96
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
Θ1		5°	
Θ2		4°	
Θ3		4°	

Mechanical Dimensions D²PAK



Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.47	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1	1.17	1.27	1.37
c	0.31	0.38	0.61
c1	1.17	1.27	1.37
D	8.50	8.70	8.90
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.31
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	1.30		2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

Mechanical Dimensions ITO-220AC



SYMBOL	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e	-	2.55	-
e1	5.00	5.10	5.16
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
L4	-	1.10	1.50
ΦP1(上口)	3.30	3.50	3.70
ΦP2(下口)	2.99	3.19	3.39
Q	2.50	2.70	2.90
θ1		5°	
θ2		4°	
θ3		10°	
θ4		5°	
θ5		5°	



ST30100
STB30100
STF30100

Technical Data
Data Sheet N1046, Rev. C



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